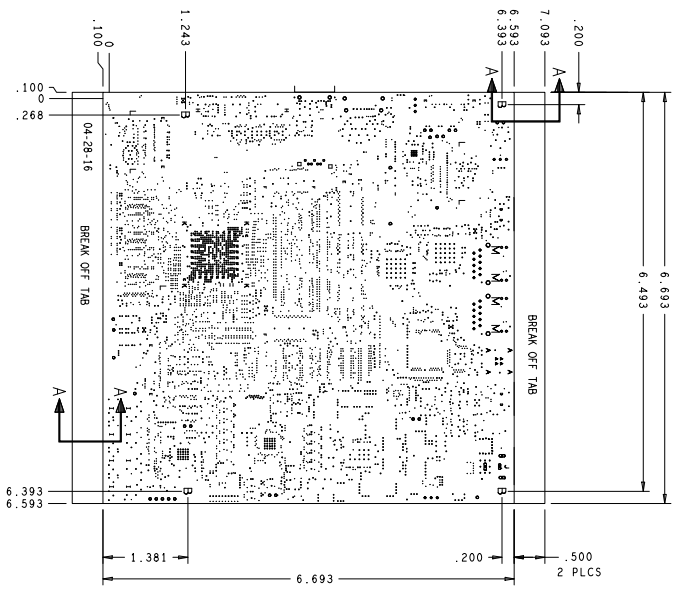
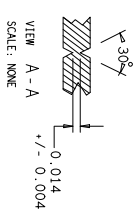


- TSLK
- SMC
- LAYER 1
- LAYER 2
- LAYER 3
- LAYER 4
- LAYER 5
- LAYER 6
- LAYER 7
- LAYER 8
- LAYER 9
- LAYER 10
- LAYER 11
- LAYER 12
- LAYER 13
- LAYER 14
- LAYER 15
- LAYER 16
- SMS
- BULK

LAYER SCHEDULE
SCALE: NONE



- NOTES: UNLESS OTHERWISE SPECIFIED
1. TOTAL BOARD THICKNESS SHALL BE .080 +/- 10% INCHES. ALL MATERIAL SHALL BE NEMA GRADE FR-4 OR EQUIVALENT. (Tg>=170 DEG. C)
 2. REFER TO STACKUP DRAWING FOR COPPER WEIGHT. AVERAGE COPPER ON THE WALL OF THE PLATED HOLE SHALL BE PER IPC CLASS 2.
 3. MINIMUM CLEARANCE ON THE BOARD SHALL BE 3.0 MILS.
 4. MINIMUM TRACE WIDTH ON THE BOARD SHALL BE 3.0 MILS. SOLDERMASK ON BOTH SIDES OF THE BOARD SHALL BE S.M.O.B.C., LPI, COLOR GREEN.
 5. PLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .003 INCH. UNPLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .002 INCH.
 6. DRC'S MUST BE RUN ON THE GERBERS BEFORE BUILDING BOARDS UNLESS PRIOR APPROVAL IS GIVEN IN WRITING.
 7. FINISHED BOARD SHALL BE FREE OF BURRS ON EDGES.
 8. SURFACE FINISH SHALL BE IMMERSION GOLD.
 9. IMPEDANCE CONTROL: REFER TO STACKUP DRAWING FOR IMPEDANCE CONTROL.



DRILL CHART					
ALL UNITS ARE IN MILLS					
FIGURE	SIZE	PLATED	QTY	TOL	NOTE
1	8.0	PLATED	3040		
2	10.0	PLATED	2039		
3	12.0	PLATED	183		
4	13.0	PLATED	16		
5	29.0	PLATED	7		
6	38.0	PLATED	37		
7	39.0	PLATED	4		
8	40.0	PLATED	26		
9	51.0	PLATED	6		
10	53.0	PLATED	2		
11	62.0	PLATED	4		
12	61.0	PLATED	4		
13	125.0	PLATED	4		
14	34.0	NON-PLATED	2		
15	35.0	NON-PLATED	4		
16	40.0	NON-PLATED	8		
17	41.0	NON-PLATED	4		
18	47.0	NON-PLATED	2		
19	61.0	NON-PLATED	2		
20	63.0	NON-PLATED	8		
21	63.0	NON-PLATED	1		
22	69.0	NON-PLATED	4		
23	93.0	NON-PLATED	5		
24	126.0	NON-PLATED	4		
25	11.0	PLATED	1		
26	11.0	PLATED	2		
27	11.0	PLATED	1		

APPROVED		SPECTRUM DIGITAL	
CHECKED	TK	FABRICATION DRAWING.	
DRAFTING	TK	J6 ECO EVM	
DATE	04-28-16	SCALE: NONE	
DESIGN ENGR		SHEET 1 OF 1	
PROJECT ENGR		517501 REV D	
ENGR MGR			
NEXT ASSEMBLY			

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